

## **Pac Tech USA Receives ITAR Certification**

**Santa Clara, Calif. — February 9, 2009** — PacTech USA announces that it has successfully received ITAR (International Traffic in Arms Regulations) certification for its Santa Clara, California manufacturing facility. ITAR is the agency within the US Department of State that regulates the manufacture, export, and transfer of defense related articles, information, and services. This certification is a requirement for many defense related manufacturing and development programs. Thorsten Teutsch, PacTech's President, noted: "PacTech is committed to providing the highest quality Advanced Packaging services and equipment to our customers. Our unique position within the industry to provide a full turnkey solution for high volume, prototyping, and quick turn manufacturing services, has lead to us working with of a significant number of defense related companies. Being ITAR certified allows us to be well positioned to support these programs."

PacTech's Santa Clara division is structured to provide both quick turn and prototyping services in addition to its high volume capabilities. The ability to process both full wafers and individual die through a complete line of packaging and backend processes, allows PacTech to meet the technical and logistical challenges associated with many defense and government related programs. PacTech has a highly knowledgeable engineering staff which can move a program though all its various phases; from concept and design, through research and development, to full volume production. PacTech employs a set of maskless technologies for UBM deposition and solder bumping which enables PacTech to provide same day services for many applications. This process flexibility allows PacTech to create flip chip, WLCSP, and BGA sized bumps (60-760µm) at very high yields.

PacTech is an international company founded in 1995 with manufacturing facilities in the United States, Germany, Japan, and Malaysia. PacTech is a world-leader in low-cost Wafer Level Packaging services, and specializes in electroless nickel under-bump metallization and solder sphere placement at both the wafer and die level. PacTech also offers a wide array of backend services including: redistribution, wafer dicing, back-grinding, backside laser marking, high speed die sort, and assembly. In addition to its contract manufacturing services, PacTech designs and manufactures a complete line of equipment for electroless nickel under-bump metallization and solder bumping. Since its inception, Pac Tech has received more than 50 patents for products in areas relating to wafer bumping, chip-scale packaging, and laser-bonding technology. Please visit our web site [www.pactech.com](http://www.pactech.com).

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